#### 2200545

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DIN rail housing, Lower housing part with metal foot catch, tall design, with vents, width: 90.4 mm, height: 99 mm, depth: 107.3 mm, color: light grey (similar RAL 7035), cross connection: DIN rail connector (optional), number of positions cross connector: 5

### Your advantages

- Tool-free mounting
- Available in overall widths from 12.5 mm to 90 mm, modular extension possible
- · Flammability rating V0 in accordance with UL 94
- · Variety of connection technology
- · Can be mounted on the DIN rail
- With integrated or DIN-rail-mountable bus connector as an option

### Commercial data

Item number	2200545
Packing unit	10 pc
Minimum order quantity	10 pc
Note	Made to order (non-returnable)
Sales key	AC08
Product key	ACHAAC
Catalog page	Page 669 (C-1-2013)
GTIN	4046356608107
Weight per piece (including packing)	95.93 g
Weight per piece (excluding packing)	94 g
Customs tariff number	85389099
Country of origin	DE

2200545

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## Technical data

### Notes

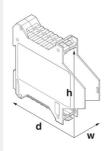
General	Refer to the data sheet for the range in the download area.
General	Material of contact pads for bus connector, galvanic gold (hard gold)

### Product properties

Туре	Lower housing parts with vents, housing cover necessary to complete the module
Product type	Enclosure bottom part
Housing series	ME
Product family	MEUT TBUS
Туре	Lower housing part with metal foot catch, tall design
Housing type	DIN rail housing
Ventilation openings present	yes

### Dimensions

Dimensional drawing



Width	90.4 mm
Height	99 mm
Depth	107.3 mm
Depth from top edge of DIN rail	100.7 mm
Depth from top edge of DIN rail to support point on upper part	68.5 mm

#### PCB design

PCB thickness	1.4 mm 1.8 mm
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#### Material specifications

Color (Housing)	light grey (RAL 7035)
Flammability rating according to UL 94	VO
CTI according to IEC 60112	600
Surface characteristics	untreated
Housing material	Polyamide

### Environmental and real-life conditions

Power dissipation single housing for 20  $^\circ\text{C}$ 

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2200545

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Ambient temperature	20 °C
Reduction factor	1
Mounting position	vertical
Power dissipation	10.4 W
Power dissipation single housing for 30 °C	
Ambient temperature	30 °C
Reduction factor	0.91
Mounting position	vertical
Power dissipation	9.5 W
Power dissipation single housing for 40 °C	
Ambient temperature	40 °C
Reduction factor	0.81
Mounting position	vertical
Power dissipation	8.4 W
Power dissipation single housing for 50 °C	
Ambient temperature	50 °C
Reduction factor	0.7
Mounting position	vertical
Power dissipation	7.3 W
Power dissipation single housing for 60 °C	
Ambient temperature	60 °C
Reduction factor	0.57
Mounting position	vertical
Power dissipation	5.9 W
Power dissipation single housing for 70 °C	
Ambient temperature	70 °C
Reduction factor	0.49
Mounting position	vertical
Power dissipation	5.1 W
Vibration test	
Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.15 mm (10 Hz 58.1 Hz)
Acceleration	2g (58.1 Hz 150 Hz)
Test duration per axis	2.5 h
Test directions	X-, Y- and Z-axis
Glow-wire test	
	IEC 60695-2-11:2014-02
Specification	120 00035-2-11.2014-02



#### 2200545

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hermal stability / ball thrust test	
Specification	IEC 60695-10-2:2014-02
Temperature	125 °C
Test duration	1 h
Force	20 N
echanical strength / tumbling barrel	
Specification	IEC 60998-1:2002-12
Height of fall	50 cm
Frequency	10
hocks	
Specification	IEC 60068-2-27:2008-02
Pulse shape	Half-sine
Acceleration	15g
Shock duration	11 ms
Number of shocks per direction	3
Test directions	X-, Y- and Z-axis (pos. and neg.)
egree of protection (IP code) Specification	
Specification	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0
Specification mbient conditions Max. IP code to attain Ambient temperature (operation)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0           IP20           -40 °C 105 °C (depending on power dissipation)
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C         80 %
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C         80 %
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C         80 %
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C         80 %
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C         80 %         4         Insertion (optional latching by PCB stop)         1.4 mm 1.8 mm
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB Unting Mounting type Mounting position	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C         80 %         Insertion (optional latching by PCB stop)         1.4 mm 1.8 mm         DIN rail mounting
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting Mounting type	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0         IP20         -40 °C 105 °C (depending on power dissipation)         -40 °C 55 °C         -5 °C 100 °C         80 %         Insertion (optional latching by PCB stop)         1.4 mm 1.8 mm         DIN rail mounting

2200545

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## Classifications

### ECLASS

	ECLASS-11.0	27182702	
	ECLASS-13.0	27190601	
E٦	ETIM		
	ETIM 9.0	EC001031	
UNSPSC			
	UNSPSC 21.0	31261500	

2200545

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## Environmental product compliance

China RoHS	Environmentally friendly use period: unlimited = EFUP-e
	No hazardous substances above threshold values

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Phoenix Contact USA 586 Fulling Mill Road Middletown, PA 17057, United States (+717) 944-1300 info@phoenixcon.com